DUSEU

MARKING DIAGRAMS

Single Inverter with Open Drain Output

NLV17SZ06

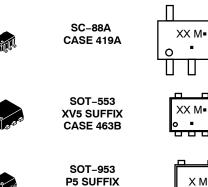
The NLV17SZ06 is a single inverter with open drain output in tiny footprint packages.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.1 ns t_{PD} at $V_{CC} = 5 V (typ)$
- Input/Output Overvoltage Tolerant up to 5.5 V
- IOFF Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in SC-88A, SOT-553 and SOT-953
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol



CASE 527AE

XX

Μ





- = Date Code*
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.



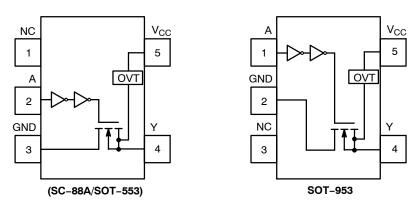


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553)

PinFunction1NC2A3GND4Y5V_{CC}

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	А
2	GND
3	NC
4	Y
5	V _{CC}

FUNCTION TABLE

A Input	Y Output		
L	Z		
Н	L		

MAXIMUM RATINGS

Symbol	Chara	Value	Unit	
V _{CC}	DC Supply Voltage		–0.5 to +7.0	V
V _{IN}	DC Input Voltage		–0.5 to +7.0	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0	V
	DC Output Voltage	(NL17SZ06P5T5G-L22088 Only)	–0.5 to V _{CC} + 0.5	
۱ _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
	DC Output Diode Current	(NL17SZ06P5T5G-L22088 Only)	±50	
I _{OUT}	DC Output Source/Sink Current	±50	mA	
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or 0	±100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for	or 10 secs	260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC-88A SOT-553 SOT-953	377 324 254	°C/W
PD	Power Dissipation in Still Air	SC-88A SOT-553 SOT-953	332 386 491	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Applicable to devices with outputs that may be tri-stated.

Provide to develop with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics			Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 5.5 5.5	V
	DC Output Voltage	(NL17SZ06P5T5G-L22088 Only)	0	V _{CC}	
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 3.0 V to 3.6 V V _{CC} = 4.5 V to 5.5 V	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			Vcc	Т	A = 25°	С	–55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input Volt	age	1.65 to 1.95	0.75 x V _{CC}	-	-	0.75 x V _{CC}	-	V
			2.3 to 5.5	$0.70 \times V_{CC}$	-	-	$0.70 \times V_{CC}$	-	
V _{IL}	Low-Level Input Volta	age	1.65 to 1.95	-	-	0.25 x V _{CC}	-	$0.25 \times V_{CC}$	V
			2.3 to 5.5	-	-	0.30 x V _{CC}	-	0.30 x V _{CC}	
V _{OL}	Low-Level Output Voltage		1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	1.65 to 5.5	-	-	±0.1	-	±1.0	μA
I _{OZ}	3-State Output Leakage Current	V _{OUT} = 0 V to 5.5 V	1.65 to 5.5	-	-	±0.5	-	±5.0	μA
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	-	-	1.0	-	10	μA
	Power Off Leakage Current (NL17SZ06P5T5G– L22088 Only)	V _{IN} = 5.5 V	0	_	-	1.0	_	10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	-	-	1.0	-	10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

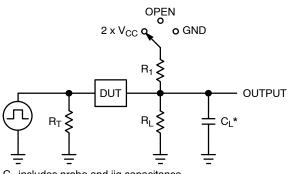
AC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C		–55°C ≤ T _A ≤ 125°C			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PZL}	Propagation Delay,		1.65 to 1.95	-	6.0	9.0	-	9.5	ns
	A to Y (Figures 3 and 4)		2.3 to 2.7	-	3.6	6.1	-	6.5	
			3.0 to 3.6	-	2.7	5.6	-	6.0	
			4.5 to 5.5	-	2.1	4.4	-	4.8	
t _{PLZ}	Propagation Delay,		1.65 to 1.95	-	4.0	9.0	-	9.5	ns
	A to Y (Figures 3 and 4)		2.3 to 2.7	-	2.8	6.1	-	6.5	
		3.0 to 3.6	-	2.5	5.6	-	6.0		
			4.5 to 5.5	-	2.2	4.4	_	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V _{CC} = 3.3 V, V _{IN} = 0 V or V _{CC} 10 MHz, V _{CC} = 5.5 V, V _{IN} = 0 V or V _{CC}	9 11	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

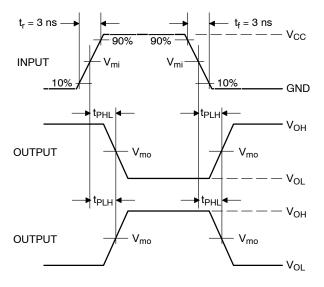


Switch Position	C _L , pF	R_{L}, Ω	R ₁ , Ω		
Open	See AC Characteristics Table				
$2 \times V_{CC}$	50	500	500		
GND	50	500	500		
	Position Open 2 x V _{CC}	Position Entropy Open See AC Character 2 x V _{CC} 50	Position End Open See AC Characteristics Tat 2 x V _{CC} 500		

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit



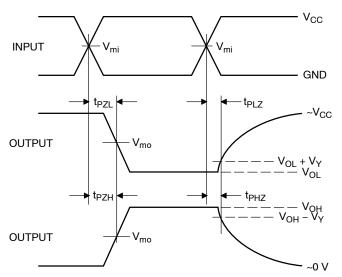


Figure 4. Switching Waveforms

		Vm	V _{mo} , V		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V	
1.65 to 1.95	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15	
2.3 to 2.7	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15	
3.0 to 3.6	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3	
4.5 to 5.5	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3	

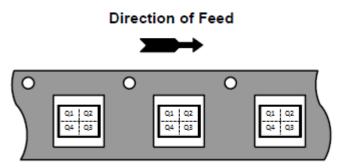
DEVICE ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
NLV17SZ06DFT2G*	SC-88A	LF	Q4	3000 / Tape & Reel
NL17SZ06XV5T2G-L22087	SOT-553	LF	Q4	4000 / Tape & Reel
NL17SZ06P5T5G-L22088	SOT-953	A (Rotated 180°)	Q2	8000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

Specifications Brochure, BRD8011/D. *NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

Pin 1 Orientation in Tape and Reel

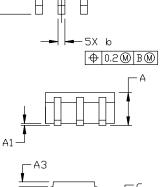


PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE. NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

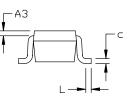


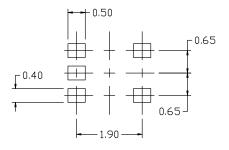
D

Е

е

F1





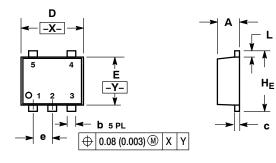
RECOMMENDED Mounting footprint

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

DIM	MILLIMETERS				
INIT	MIN.	NDM.	MAX.		
А	0.80	0.95	1.10		
A1			0.10		
A3	0.20 REF				
b	0.10	0.20	0.30		
С	0.10		0.25		
D	1.80	2.00	5.20		
E	2.00	2,10	5.20		
E1	1.15	1.25	1.35		
e	0.65 BSC				
L	0.10	0.15	0.30		

PACKAGE DIMENSIONS

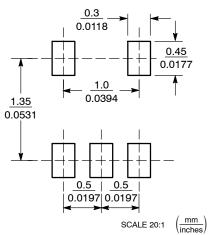
SOT-553, 5 LEAD CASE 463B **ISSUE C**



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.50	0.55	0.60	0.020	0.022	0.024	
b	0.17	0.22	0.27	0.007	0.009	0.011	
С	0.08	0.13	0.18	0.003	0.005	0.007	
D	1.55	1.60	1.65	0.061	0.063	0.065	
Е	1.15	1.20	1.25	0.045	0.047	0.049	
е		0.50 BSC			0.020 BSC)	
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	1.55	1.60	1.65	0.061	0.063	0.065	

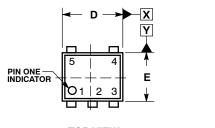
RECOMMENDED SOLDERING FOOTPRINT*



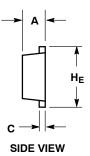
*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

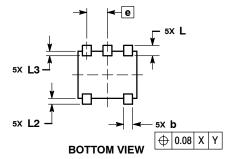
PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E



TOP VIEW





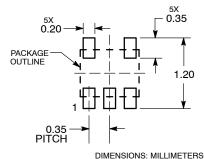
NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE 3.

MINIMUM THICKNESS OF THE BASE MATERIAL DIMENSIONS D AND E DO NOT INCLUDE MOLD 4. FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.34	0.37	0.40
b	0.10	0.15	0.20
С	0.07	0.12	0.17
D	0.95	1.00	1.05
Е	0.75	0.80	0.85
е	0.35 BSC		
HE	0.95	1.00	1.05
Г	0.175 REF		
L2	0.05	0.10	0.15
L3			0.15

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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